

# NEW PRODUCT

# 8329HTC

## Thermally Conductive Structural Epoxy Adhesive



8329HTC is a 2-part structural epoxy adhesive that features superior bonding strength, high thermal conductivity, robust operating temperature range and high dimensional stability. The epoxy is a thixotropic paste with minimal flow, allowing localized application into tight spaces. Once cured, the epoxy is tough and rigid, protecting the bonded area from physical impacts, shocks, and vibration. It also withstands exposure to chemicals, fungus, salt water, humidity and corrosive gases, making it suitable for use in harsh environments.

Superior tensile, compressive and lap shear strength

Low coefficient of thermal expansion

Strongly bonds to metal, plastic, glass and wood

Room temperature curing

Strong resistance to humidity, salt water, chemicals and corrosive gas



### Applications

- Bonding heat sinks
- Power semiconductor devices
- Flip chip BGA heat spreaders
- Battery modules and packs
- LED lightings
- Power Supplies

### Available Packaging

- |               |                |               |
|---------------|----------------|---------------|
| 8329HTC-50ML  | Dual Cartridge | 45 mL, 77 g   |
| 8329HTC-400ML | Dual Cartridge | 373 mL, 635 g |

### Links

-  [Technical Data Sheet](#)
-  [Safety Data Sheet](#)
-  [Category Data Sheet](#)
-  [Technical Inquires](#)